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Attorney Docket No. 5649-1

**PATENT** 

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Park et al. Serial No.: 10/615,362 Examiner: H. Jey Tsai Group Art Unit: 2812 Confirmation No.: 8781

Filed: July 8, 2003

METHODS FOR FORMING A METAL CONTACT IN A SEMICONDUCTOR

DEVICE IN WHICH AN OHMIC LAYER IS FORMED WHILE FORMING A

BARRIER METAL LAYER

Date: August 4, 2004

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## **AMENDMENT**

Sir:

Applicants provide the present Amendment to address the issues raised in the Official Action (hereinafter "the Action") mailed May 4, 2004.

Amendments to the Claims are reflected in the listing of claims, which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.

It is not believed that an extension of time and/or additional fee(s)-including fees for net addition of claims-are required, beyond those that may otherwise be provided for in documents accompanying this paper. In the event, however, that an extension of time is necessary to allow consideration of this paper, such an extension is hereby petitioned under 37 C.F.R. §1.136(a). Any additional fees believed to be due in connection with this paper may be charged to our Deposit Account No. 50-0220.